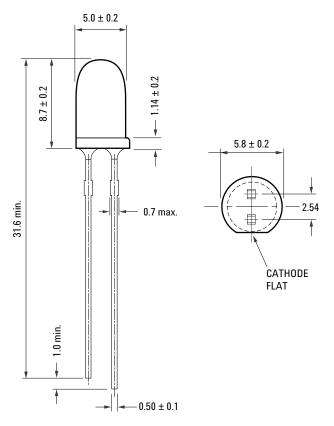


Datasheet

Description

The HSDL-4260 High Power Infrared emitter was designed for applications that require high power, low forward voltage and high speed. It utilizes Aluminum Galium Arsenide (AlGaAs) LED technology and is optimized for speed and efficiency at emission wavelengths of 875nm. The material used produces high radiant efficiency over a wide range of currents. The emitter is packaged in clear T-1¾ (5mm) package.



Features

- High Power AlGaAs LED Technology
- 875nm Wavelength
- T-1¾ Package
- Low Cost
- Low Forward Voltage: 1.4V at 20mA
- High Speed: 15ns Rise Times

Applications

- Industrial Infrared Equipments and applications
- Portable Infrared Instruments
- Consumer Electronics (Optical mouse, Infrared Remote Controllers etc)
- High Speed Infrared Communications (IR LANs, IR Modems, IR Dongles etc)

| Part Number | Lead Form | Shipping Option | | |
|-------------|-----------|-----------------|--|--|
| HSDL-4260 | Straight | Bulk | | |

Absolute Maximum Ratings at 25°C

| Parameter | Symbol | Minimum | Maximum | Unit | Reference Figure 3 Duty cycle = 20% Pulse Width = 100us | |
|----------------------------|-------------------|---------|---------------|------|---|--|
| Peak Forward Current | I _{FPK} | - | 500 | mA | | |
| Forward Current | I _{FDC} | - | 100 | mA | [1] | |
| Power Dissipation | P _{DISS} | - | 230 | mW | | |
| Reverse Voltage | V_R | 4 | - | V | I _R =100uA | |
| Storage Temperature | Ts | -40 | 100 | °C | | |
| LED Junction Temperature | T _J | | 110 | °C | | |
| Lead Soldering Temperature | | | 260 for 5 sec | °C | | |

Notes: Derate as shown in Figure 6.

Recommended Operating Conditions

| Parameter | Symbol | Min | Max | Unit | Reference |
|-----------------------|--------|-----|-----|------|-----------|
| Operating Temperature | T_0 | -40 | 85 | °C | |

Electrical Characteristics at 25°C

| Parameter | Symbol | Min. | Тур. | Max. | Unit | Condition | Reference |
|--|----------------|------|------------|------------|-------|---|-----------|
| Forward Voltage | V_{F} | - | 1.4 1.7 | 1.9 2.3 | V | I _{FDC} =20mA I _{FDC} =100mA | Figure 2 |
| Forward Voltage Temperature Coefficient | ΔV/ΔΤ | - | -1.3 | - | mV/°C | I _{FDC} =100mA | Figure 4 |
| Series Resistance | R _s | - | 4 | - | Ohms | I _{FDC} =100mA | |
| Diode Capacitance | Co | - | 70 | - | pF | V _{bias} =0V, f=1MHz | |
| Thermal Resistance, Junction to Ambient | $R\theta_{ja}$ | - | 300 | - | °C/W | | |

Optical Characteristics at 25°C

| Parameter | Symbol | Min. | Тур. | Max. | Unit | Condition | Reference |
|---|---------------------------|------|-------|------|-------|--|-----------|
| Radiant On-Axis Intensity | I _E | 150 | 200 | - | mW/Sr | I _{FDC} =100mA | Figure 5 |
| Radiant On-Axis Intensity Temperature Coefficient | $\Delta I_{E}/\Delta T$ | - | -0.36 | - | %/°C | I _{FDC} =100mA | |
| Viewing Angle | 2 θ _{1/2} | - | 15 | - | 0 | | Figure 7 |
| Peak Wavelength | λ_{pk} | - | 875 | - | nm | | Figure 1 |
| Peak wavelength Temperature Coefficient | Δλ/ΔΤ | - | 0.2 | - | nm/°C | I _{FDC} =100mA | |
| Spectral Width | Δλ | | 45 | - | nm | I _{FDC} =20mA | Figure 1 |
| Optical Rise and Fall Time | t,/t _f | | 15 | - | ns | I _{FDC} =500mA Duty Ratio = 20% Pulse Width=100ns | |

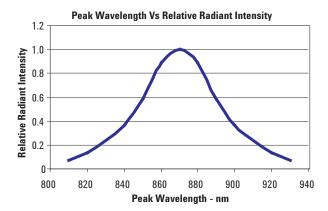


Figure 1. Relative Radiant Intensity vs. Wavelength

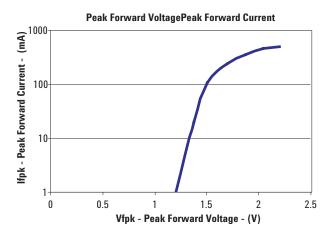


Figure 3. Peak Forward Current vs. Forward Voltage

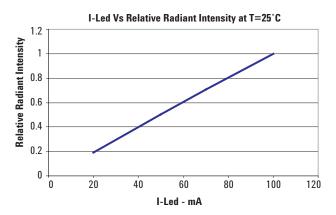


Figure 5. Relative Radiant Intensity vs. DC Forward Curren

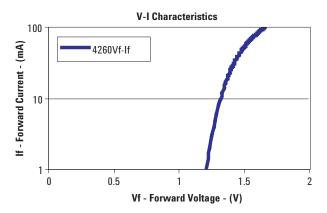


Figure 2. DC Forward Current vs. Forward Voltage

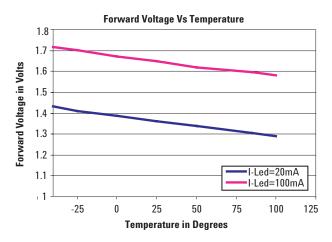


Figure 4. Forward Voltage vs. Ambient Temperature

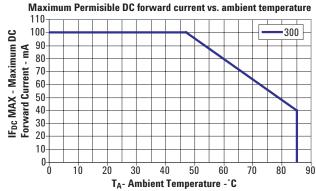
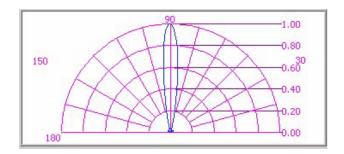


Figure 6. DC Forward Current vs. Ambient Temperature Derated Based on TJMAX=110°C



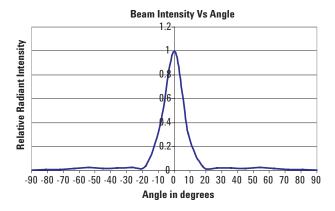


Figure 7. Radiant Intensity vs. Angular Displacement for HSDL-4260